

1983 IBM (CMP: Chemical Mechanical Planarization) 가 가 Slurry Device가 Wafer , . CMP (Slurry, Pad, Conditioning disc) , CMP . CMP CMP polisher, post CMP cleaner , Slurry Endpoint Detetction , CMP Slurry Pad . Slurry , Slurry Slurry Pad 가 Slurry , CMP , Pad, Slurry , 가 . CMP 가 ,

CMP , , . WIPS , 1986 1 1 2006 4 30 가 , , , . CMP Slurry Pad 3가 가 , CMP CMP polisher, post CMP cleaner , Slurry endpoint detetction , CMP Slurry Pad .



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CMP		CMP Polisher	Polisher Head design	
			Polisher Head Platen	
			ECMP polisher /	
			Pad Conditioner Disk /	
		Post CMP Cleaner	Post CMP Cleaner	
			End point detection	
			Slurry	
		Pad	Pad	Pad
				Pad
				Pad
	Pad 가		Groove 가 Groove Shape Design	
			Pad Pore	
			Pad	
			Pad Abrasive Particle /ECMP Pad	
	Slurry		CMP Slurry (STI)	Abrasive Particle ,
		Impurity Abrasive Particle Filtration		
		pH 가		
		Metal CMP Slurry (W, Al, Cu, Ru)	Abrasive Particle Slurry	
			Metal CMP Chemical 가	
			ECMP Electrolyte 가	
Impurity Abrasive Particle Filtration				

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